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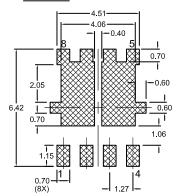
BOTTOM VIEW

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rights of others.



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RECOMMENDED LAND PAD

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM	 XXXXXX = Specific Device A = Assembly Locat WL = Wafer Lot Y = Year W = Work Week *This information is generic. F to device data sheet for actumarking. Some products ma the Generic Marking. 	ion Please refer Jal part		
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DESCRIPTION:	LFPAK8 5.15x6.15		PAGE 1 OF 1	
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- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS, MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
- 4. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT 5. DATUM PLANE H.
- 6. OPTIONAL MOLD FEATURE.

	MILLIMETERS				
DIM	MIN	NOM	MAX		
A	1.10	1.20	1.30		
A1	0.00	0.08	0.15		
A2	1.10	1.15	1.20		
A3	0.25 REF				
A4	0.45	0.50	0.55		
b	0.40	0.45	0.50		
С	0.19	0.22	0.25		
c2	0.19	0.22	0.25		
D	4.70	4.80	4.90		
D1	3 <u>.</u> 80	4.00	4.20		
D2	3.00	3.10	3.20		
D3	0.30	0.40	0.50		
Е	4.80	4.90	5.00		
E1	3.90	4.00	4.10		
E2	5.00	5.15	5.30		
е	1.270 BSC				
e/2	0.635 BSC				
G H	0.55	0.65	0.75		
Н	6.00	6.15	6.30		
k	0.40	0.50	0.60		
L	0.45	0.65	0.85		
L1	0.15	0.25	0.35		
L2	0.90	1.10	1.30		
q	0°	4°	8°		

DATE 30 OCT 2019